

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
16 October 2003 (16.10.2003)

PCT

(10) International Publication Number
WO 03/085725 A2

(51) International Patent Classification⁷: **H01L 23/00**

(21) International Application Number: PCT/US03/09017

(22) International Filing Date: 26 March 2003 (26.03.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/113,502 1 April 2002 (01.04.2002) US

(71) Applicant: **INTEL CORPORATION** [US/US]; 2200
Mission College Boulevard, Santa Clara, CA 95052 (US).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(72) Inventors: **ESKILDSEN, Steven**; 307 Oak Canyon Way, Folsom, CA 95620 (US). **MILLS, Duane**; 6017 Dodson Road, Shingle Springs, CA 95682 (US).

Published:
— *without international search report and to be republished upon receipt of that report*

(74) Agents: **TROP, Timothy, N.**; Trop, Pruner & Hu, P.C., Suite 100, 8554 Katy Freeway, Houston, TX 77024 et al. (US).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: PROVIDING IN PACKAGE POWER SUPPLIES FOR INTEGRATED CIRCUITS

(57) Abstract: A device (14) with an in package power supply (16) may be utilized to supply power to other components (20). As a result, the overall system (10) size may be reduced and economies may be achieved.



WO 03/085725 A2